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(71) Applicant (for all designated States except US): **ENTEGRIS, INC.** [US/US]; 3500 Lyman Boulevard, Chaska, MN 55318 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **BHATT, Sanjiv, M.** [IN/US]; 5894 Red Cherry Lane, Minnetonka, MN 55345 (US). **EGGUM, Shawn, D.** [US/US]; 1458 82nd Street, Victoria, MN 55386 (US).

(74) Agents: **CHRISTENSEN, Douglas, J.** et al.; Patterson, Thuente, Skaar & Christensen, P.A., 4800 IDS Center, 80 South Eighth Street, Minneapolis, MN 55402-2100 (US).

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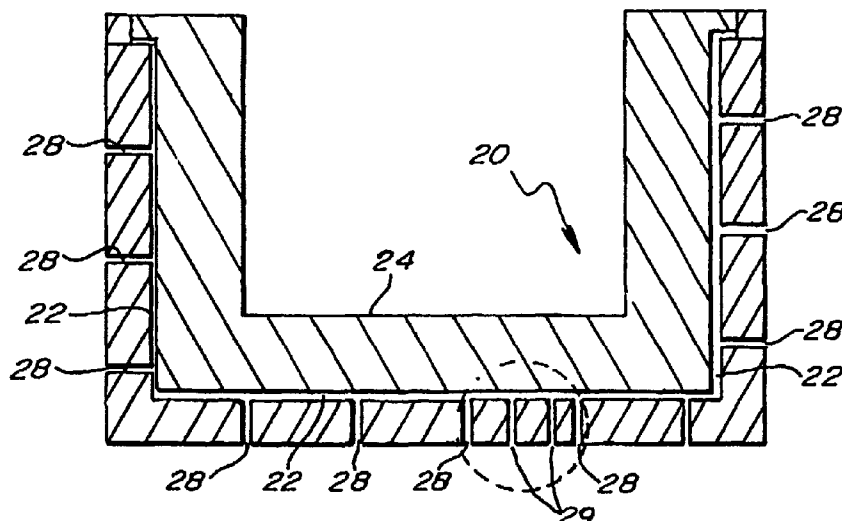
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(54) Title: SEMICONDUCTOR COMPONENT HANDLING DEVICE HAVING A PERFORMANCE FILM



(57) **Abstract:** The present invention relates generally to a system and method for including a thin protective containment thermopolymer film, such as PEEK, in the molding process for handlers, transporters, carriers, trays and like devices utilized in the semiconductor processing industry. The thermoplastic film of predetermined size and shape is selectively placed along a shaping surface in a mold cavity for alignment with a desired target surface of a moldable material. The molding process causes a surface of the film to bond to a contact surface of the moldable material such that the film is permanently adhered to the moldable material. As a result, a compatible polymer film can be selectively bonded only to those target surfaces where performance characteristics such as abrasion resistance, heat resistance, chemical resistance, outgassing containment, rigidity enhancement, hardness, creep reduction, fluid absorption containment, and the like is needed.



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